

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (previously presented): A method for producing an aluminum/ceramic bonding substrate, said method comprising the steps of:

causing a solid aluminum member having a purity of 99.9% or more to contact at least one side of a ceramic substrate; and  
thereafter, heating the solid aluminum member and the ceramic substrate, which contacts the solid aluminum member, at a temperature of 620 to 650 °C in an inert gas to bond the solid aluminum member directly to the ceramic substrate.

Claim 2 (previously presented): A method for producing an aluminum/ceramic bonding substrate, said method comprising the steps of:

causing a solid aluminum member having a purity of 99.5% or more to contact at least one side of a ceramic substrate; and  
thereafter, heating the solid aluminum member and the ceramic substrate, which contacts the solid aluminum member, at a temperature of 620 to 650°C in an inert gas to bond the solid aluminum member directly to the ceramic substrate,

wherein said ceramic substrate is a ceramic substrate containing aluminum nitride as a principal component.

Claim 3 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said ceramic

substrate is a ceramic substrate containing alumina as a principal component.

Claim 4 (cancelled).

Claim 5 (original): A method for producing an aluminum/ceramic bonding substrate as set forth in claim 1, wherein said inert gas is nitrogen gas.

Claim 6-10 (canceled).